

## **Inductors for power circuits**

Size 3.2 x 2.5 x 2.5 (mm)

**Series/Type:** CLT32

**Date:** March 2022

**Construction**

- Thick copper frame
- Molded metal solution
- No internal connection


**Features**

- High current, low DC resistance
- Temperature range from  $-40\text{ }^{\circ}\text{C}$  up to  $+165\text{ }^{\circ}\text{C}$  incl. self-heating
- ESD tested up to 2 kV to AEC-Q200
- Suitable for lead-free reflow soldering as referenced in JEDEC J-STD 020D
- Qualified to AEC-Q200
- RoHS-compatible

**Applications**

- PMIC systems in automotive electronics

**Terminals**

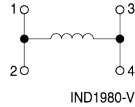
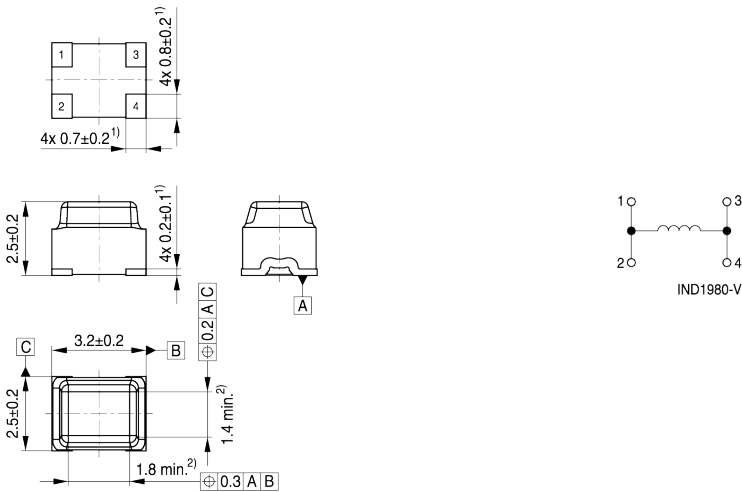
- Tinned terminals
- Layer composition Ni, Sn
- Lead-free tinned

**Marking**

- No marking on component
- Minimum data on reel:  
Manufacturer, ordering code, lot number, quantity, date of packing

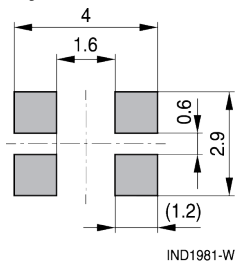
**Delivery mode and packing unit**

- 12-mm blister tape, wound on 330-mm  $\varnothing$  reel
- Packing unit: 6000 pcs./reel

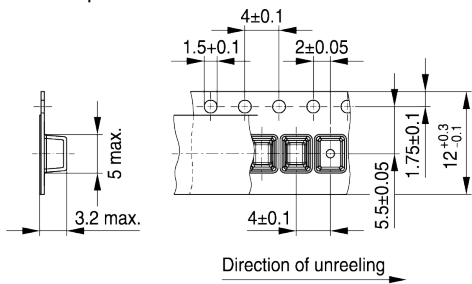
**Dimensions**


- <sup>1)</sup> Soldering area
- <sup>2)</sup> Suction area

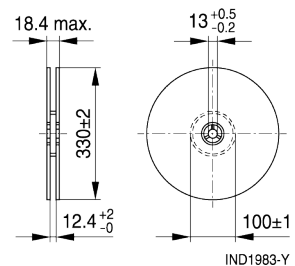
IND1762-TE

**Layout recommendation**


IND1981-W

**Taping an packing**
**Blister tape**


IND1982-X-E

**Reel**


IND1983-Y

**Technical data and measuring conditions**

Rated inductance $L_R$	Measured with Agilent 4990A at 1 MHz, 0.1 V, +23 °C ±3 °C
Inductance tolerance	±20% at +23 °C ±3 °C
Operating temperature range	-40 °C ... +165 °C
Rated current $I_{temp}$	Based on the temperature increase (temperature increase 40 K by self-heating) Ambient temperature: +23 °C Measured in 100 µm Cu thickness single layer PCB 100x40x1 mm (equivalent to multilayer PCB) Temperature rise is highly dependent on many factors and consequently, it must be verified in final application
Saturation current $I_{sat}$	Based on the inductance change rate (30% below the initial value)
DC resistance $R_{DC}$	Measured at +23 °C ±3 °C; tolerance ±15%
Solderability (lead-free)	Sn95.5Ag3.8Cu0.7: +245 °C / 5 s Method: Solder bath (Dip) Wetting of soldering area: ≥ 95%
Resistance to soldering heat	+260 °C, 40 s (as referenced in JEDEC J-STD 020D)
Climatic category	40/165/56 (to IEC 60068-1)
Storage conditions	Mounted: -40 °C ... +165 °C Packaged: -25 °C ... +40 °C, ≤ 75% RH
Weight	Approx. 120 mg

**Characteristics and ordering codes**

$L_R$	$R_{DC,typ}$	$I_{Sat,typ}$ at 23 °C	$I_{temp,typ}$ at 23 °C at +40 K temp. increase	Internal code	Ordering code
nH	mΩ	A	A		
17	0.39	60.0	45.0	B82403T0170M000	CLT32-17N
42	1.0	54.0	28.0	B82403T0420M000	CLT32-42N
55	1.0	39.5	28.0	B82403T0550M000	CLT32-55N
80	1.9	36.0	20.0	B82403T0800M000	CLT32-80N
110	1.9	29.0	20.0	B82403T0111M000	CLT32-R11
150	3.3	25.4	15.4	B82403T0151M000	CLT32-R15
200	3.3	20.5	15.4	B82403T0201M000	CLT32-R20
310	5.3	17.5	12.1	B82403T0311M000	CLT32-R31
440	7.6	13.5	10.1	B82403T0441M000	CLT32-R44

### Cautions and warnings

- Please note the recommendations in our Inductors data book (latest edition) and in the data sheets.
  - Particular attention should be paid to the derating curves given there.
  - The soldering conditions should also be observed. Temperatures quoted in relation to wave soldering refer to the pin, not the housing.
- If the components are to be washed varnished it is necessary to check whether the washing varnish agent that is used has a negative effect on the wire insulation, any plastics that are used, or on glued joints. In particular, it is possible for washing varnish agent residues to have a negative effect in the long-term on wire insulation. Washing processes may damage the product due to the possible static or cyclic mechanical loads (e.g. ultrasonic cleaning). They may cause cracks to develop on the product and its parts, which might lead to reduced reliability or lifetime.
- The following points must be observed if the components are potted in customer applications:
  - Many potting materials shrink as they harden. They therefore exert a pressure on the plastic housing or core. This pressure can have a deleterious effect on electrical properties, and in extreme cases can damage the core or plastic housing mechanically.
  - It is necessary to check whether the potting material used attacks or destroys the wire, wire insulation, plastics or glue.
  - The effect of the potting material can change the high-frequency behaviour of the components.
  - Many coating materials have a negative effect (chemically and mechanically) on the winding wires, insulation materials and connecting points. Customers are always obligated to determine whether and to what extent their coating materials influence the component. Customers are responsible and bear all risk for the use of the coating material. TDK Electronics does not assume any liability for failures of our components that are caused by the coating material.
- Ceramics / ferrites are sensitive to direct impact. This can cause the core material to flake, or lead to breakage of the core.
- Even for customer-specific products, conclusive validation of the component in the circuit can only be carried out by the customer.
- Due to product design and applied manufacturing process, appearance, symmetry, and shape of not dimensioned details could vary within same lot, as well discoloration of housing is possible. TDK does not expect detrimental effects on product function or reliability. In case of conflicts, TDK reference standard shall prevail.

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Release 2020-06

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